



Material Content Data Sheet



Sales Product Name		BSS308PE H6327		Issued		25. September 2017		
MA#		MA000949834						
Package		PG-SOT23-3-5		Weight*		9.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		468	
	noble metal	gold	7440-57-5	0.017	0.18		1816	
	inorganic material	silicon	7440-21-3	0.261	2.77	3.00	27699	29983
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		959	
	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		320	
	non noble metal	copper	7440-50-8	3.000	31.85	31.99	318467	319810
wire	non noble metal	copper	7440-50-8	0.076	0.81	0.81	8063	8063
encapsulation	organic material	carbon black	1333-86-4	0.056	0.60		5961	
	plastics	epoxy resin	-	1.207	12.82		128155	
	inorganic material	silicondioxide	60676-86-0	4.352	46.17	59.59	461956	596072
leadfinish	non noble metal	tin	7440-31-5	0.150	1.59	1.59	15883	15883
plating	noble metal	silver	7440-22-4	0.284	3.02	3.02	30189	30189
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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